Innovative Solutions With Light





ATTENTION

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Features

- ϕ 3 LAMP LED.
- •LOW POWER CONSUMPTION.
- •COMBINED VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •PACKAGE: 500PCS / BAG.

SENSITIVE

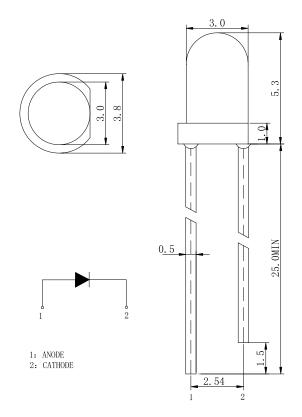


Description

MCDL-3014WC

This devices are made with TS InGaN.

Package Dimensions



Tolerance	Dimension Tolerance (UNIT:mm)				
Grade	0.5~3	3~6	6~30	30~120	
Medium(m)	±0.1	± 0.2	± 0.3	±0.5	
Chip		Lens Color			
Material	Emitting Color	- Water Clear			
InGaN	White				

SPEC NO.: REV NO.:B/2 DATE:Mar/18/2008 PAGE:1/5

M C D L - 3 0 1 4 W C

■ Absolute Maximum Rating

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	lf	20	mA
Peak Forward Current*	I FP	100	mA
Reverse Voltage	VR	5	V
Power Dissipation	Po	80	mW
Electrostatic discharge	Esp	800	V
Operation Temperature	Topr	-30∽+80	$^{\circ}\! \mathbb{C}$
Storage Temperature	Tstg	-30∽+80	$^{\circ}\!\mathbb{C}$
Lead Soldering Temperature*	Tsol	Max. 260°C for 5sec N	Лах.

^{*}IFP Conditions: Pulse Width≤10msec

■ Typical Optical/ Electrical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	
Forward Voltage	VF		2.8	3.2	3.6	V	
50% Power Angle	2θ 1/2	- I⊧=20mA		25		deg	
Luminous Intensity	lv		3770	4900		mcd	
Chromaticity	Х			0.31		X:±0.015	
coordinates	Y			0.33		Y:±0.025	
Peak Wavelength	Wavelength λD					nm	
Recommend Forward Current	I⊧(rec)				20	mA	
Reverse Current	IR	Vr=5V			10	uA	

Notes:

- 1. Absolute maximum ratings Ta=25 $^{\circ}$ C.
- 2. Tolerance of measurement of forward voltage \pm 0.1 V.
- 3. Tolerance of measurement of peak Wavelength \pm 2.0 nm.
- 4. Tolerance of measurement of luminous intensity \pm 15%.
- 5. Tolerance of measurement of angle intensity \pm 15%.

SPEC NO.: REV NO.:B/2 DATE:Mar/18/2008 PAGE:2/5

^{*}Tsol Conditions: 3mm from the base of the epoxy bulb

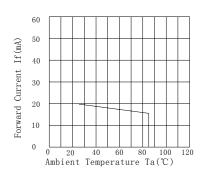
M C D L - 3 0 1 4 W C

■ Reliability Performance

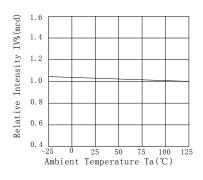
Test Items And Result

Test Classification	Test Item	Test Conditions	Test Duration	Sample Size	AC/RE
Life Test	Room Temperature DC Operating Life Test	Ta=25°C±5°C,IF=20mA	1000 hrs	22 pcs	0/1
Environment Test	Thermal Shock Test	-10°C±5°C ←→+ 100°C±5°C 5min. 10sec. 5min.	50 cycles	22 pcs	0/1
	Temperature Cycle Test	-40°C±5°C →+85 °C±5°C 30min. 5min. 30min.	50 cycles	22 pcs	0/1
	High Temperature $\&$ High Humidity Test	Ta=85 $^\circ$ ±5 $^\circ$ RH =85 $^\circ$ ±5 $^\circ$ RH	1000 hrs	22 pcs	0/1
	High Temperature Storage	Ta=100°C±5°C	1000 hrs	22 pcs	0/1
	Low Temperature Storage	Ta=-55°C ±5°C	1000 hrs	22 pcs	0/1
Mechanical Test	Resistance to Soldering Heat	Ta=230°C ±5°C	5sec.	22 pcs	0/1
	Lead Integrity	Load 2.5N(0.25kgf) 0° ~ 90° ~0°	3times	22 pcs	0/1

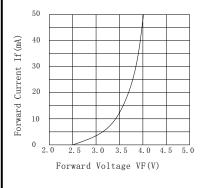
Forward Current vs. Ambient Temperature



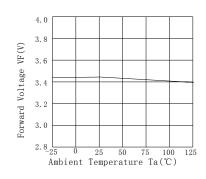
Relative Intensity vs. Ambient Temperature

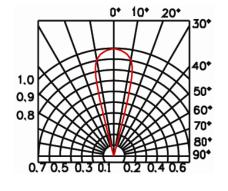


Forward Current vs. Forward Voltage



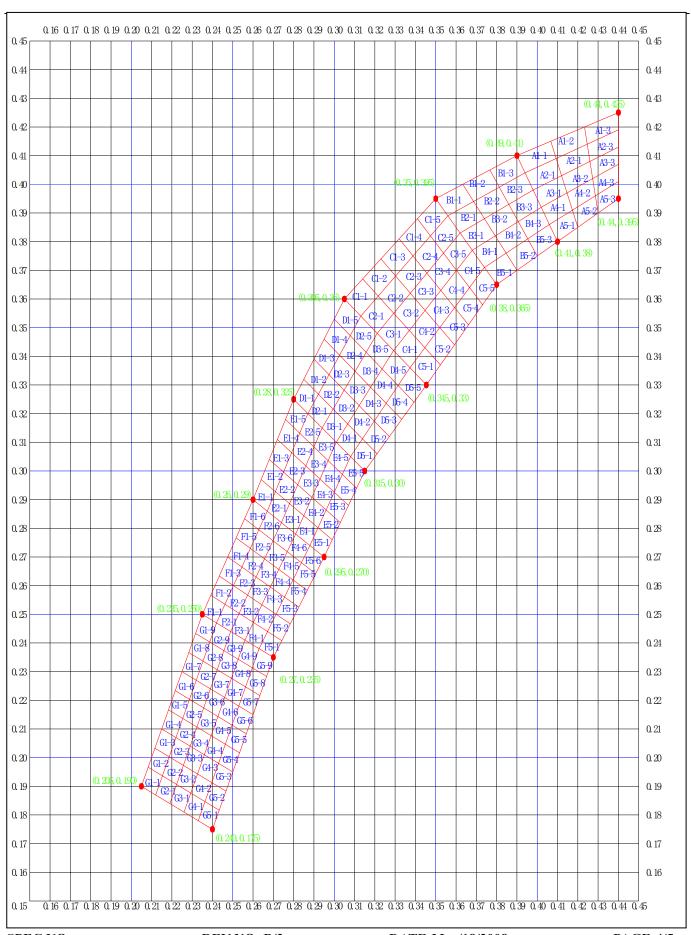
Forward Voltage vs. Ambient Temperature





SPEC NO.: REV NO.:B/2 DATE:Mar/18/2008 PAGE:3/5

M C D L - 3 0 1 4 W C



SPEC NO.: REV NO.:B/2 DATE:Mar/18/2008 PAGE:4/5

M C D L - 3 0 1 4 W C

Soldering:

1. Manual Of Soldering

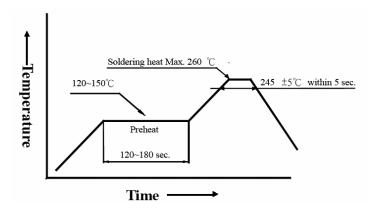
The temperature of the iron tip should not be higher than $260^{\circ}\text{C}(500^{\circ}\text{F})$ and Soldering within 3 seconds per solder-land is to be observed.

2. DIP soldering (Wave Soldering):

Preheating:120°C~150°C, within 120~180 sec.

Operation heating:245°C±5°C within 5 sec.260°C (Max)

Gradual Cooling (Avoid quenching).



Handling:

Care must be taken not to cause to the epoxy resin portion of LED while it is exposed to high temperature. Care must be taken not rub the epoxy resin portion of LED with hard or sharp article such as the sand blast and the metal hook.

Care must be taken there should be more than 3mm from jointing point to the epoxy resin.

Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the LED within the rated figures .Also caution should be taken not to overload LED with exorbitant voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures .Also the circuit should be designed so as be subjected to reverse voltage when turning off the LED.

Storage:

In order to avoid the absorption of moisture . it is recommended to solder LED as soon as possible after unpacking the sealed envelope.

If the envelope is still packed to store it in the environment as following:

Temperature: -5° C \sim 45 $^{\circ}$ C (23 $^{\circ}$ F \sim 113 $^{\circ}$ F) Humidity: RH 60% Max.

SPEC NO.: REV NO.:B/2 DATE:Mar/18/2008 PAGE:5/5